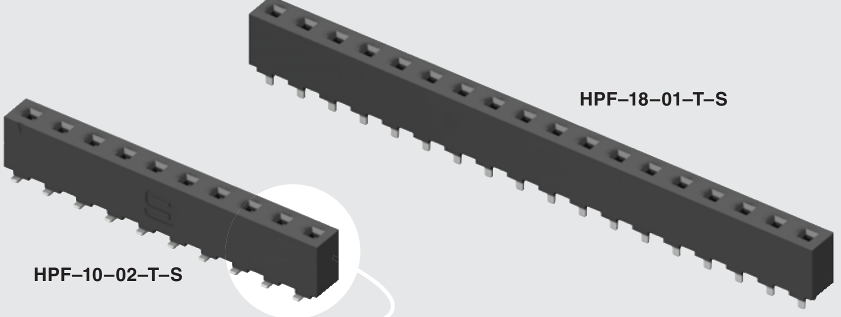


(5,08 mm) .200"

HPF SERIES

POWER SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HPF

Insulator Material:
Black LCP
Contact Material:
BeCu
Plating:
Sn over
50µ" (1,27 µm) Ni
Insertion Depth:
(3,68 mm) .145" to (8,26 mm) .325" (.368" (9,35 mm) plus board thickness minimum for bottom entry)
Wiping Distance:
(0,38 mm) .015"
Insertion Force:
(Single contact only)
56 oz (15,57 N) avg.
Withdrawal Force:
(Single contact only)
52 oz (14,46 N) avg.
Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0,15 mm) .006" max (02-10)
(0,20 mm) .008" max (11-20)
RoHS Compliant:
Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

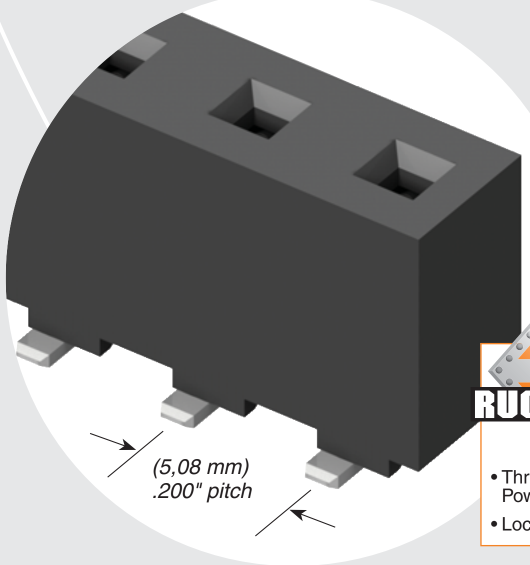
FILE NO: 090871 0 000

Note: Some lengths, styles and options are non-standard, non-returnable.

Mates with:
HPM, HPW

HPF/HPM	
PINS	CURRENT RATING (PER CONTACT)
1	16.6 A
2	14.4 A
3	13.2 A
4	12.7 A
ALL	8.9 A

Surface Mount or Through-hole



RUGGEDIZED by SAMTEC

- Three-finger Power Eye contact
- Locking clip option

HPF – NO. PINS PER ROW – LEAD STYLE – PLATING OPTION – S – OTHER OPTIONS

NO. PINS PER ROW
02 thru 20

LEAD STYLE
–01 = Through-hole
–02 = Surface Mount

PLATING OPTION
–T = Matte Tin

OTHER OPTIONS
–LC = Locking Clip (Manual placement required) (Style –02 only)
–K = (6,50 mm) .256" DIA Polyimide Film Pick & Place Pad
–TR = Tape & Reel Packaging (14 positions maximum) (Style –02 only)